

## Description

The 74LVC2G14 is a dual Schmitt trigger inverter gate with standard push-pull outputs. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I<sub>OFF</sub>. The I<sub>OFF</sub> circuitry disables the output preventing damaging current backflow when the device is powered down.

The gate performs the positive Boolean function:

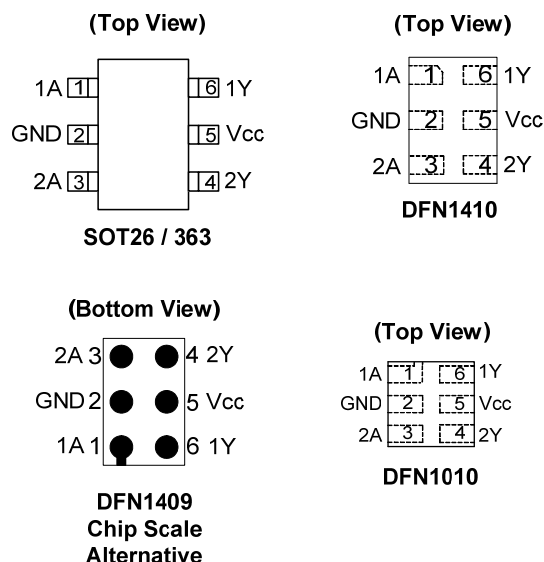
$$Y = \overline{A}$$

## Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- ±24mA Output Drive at 3.0V
- CMOS low power consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115)
  - Exceeds 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- DFN1409 package designed as a direct replacement for chip scale packaging.
- Range of Package Options SOT26, SOT353, DFN1010, DFN1409 and DFN1410
- Leadless packages per JESD30E
  - DFN1410 denoted as X2-DFN1410-6
  - DFN1409 denoted as X2-DFN1409-6
  - DFN1010 denoted as X2-DFN1010-6
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.  
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.  
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and < 1000 ppm antimony compounds.

## Pin Assignments



## Applications

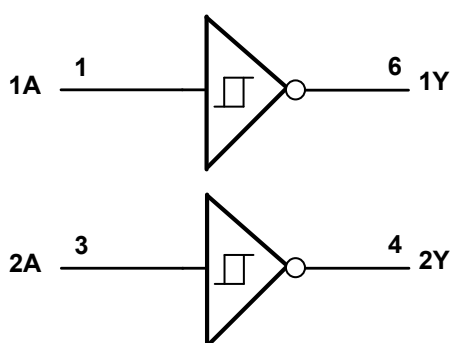
- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide array of products such as:
  - PCs, networking, notebooks, netbooks, tablets
  - Computer peripherals, hard drives, CD/DVD ROM
  - TV, DVD, DVR, set top box
  - Cell Phones, Personal Navigation / GPS
  - MP3 players, Cameras, Video Recorders

[Click here for ordering information, located at the end of datasheet](#)

## Pin Descriptions

Pin Name	Pin NO.	Function
1A	1	Data Input
GND	2	Ground
2A	3	Data Input
2Y	4	Data Output
V <sub>CC</sub>	5	Supply Voltage
1Y	6	Data Output

## Logic Diagram



## Function Table

Inputs	Output
A	Y
H	L
L	H

## Absolute Maximum Ratings (Note 4) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to +6.5	V
V <sub>I</sub>	Input Voltage Range	-0.5 to +6.5	V
V <sub>O</sub>	Voltage applied to output in high impedance or I <sub>OFF</sub> state	-0.5 to +6.5	V
V <sub>O</sub>	Voltage applied to output in high or low state	-0.3 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output Clamp Current V <sub>O</sub> < 0	-50	mA
I <sub>O</sub>	Continuous Output Current	-50	mA
—	Continuous Current Through V <sub>DD</sub> or GND	±100	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

**Recommended Operating Conditions** (Note 5) (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Symbol	Parameter		Min	Max	Unit	
$V_{CC}$	Operating Voltage	Operating	1.65	5.5	V	
		Data retention only	1.5	—	V	
$V_I$	Input Voltage		0	5.5	V	
$V_O$	Output Voltage		0	$V_{CC}$	V	
$I_{OH}$	High-Level Output Current	$V_{CC} = 1.65\text{V}$	—	-4	mA	
		$V_{CC} = 2.3\text{V}$	—	-8		
		$V_{CC} = 3\text{V}$	—	-16		
		$V_{CC} = 4.5\text{V}$	—	-24		
$I_{OL}$	Low-Level Output Current	$V_{CC} = 1.65\text{V}$	—	4	mA	
		$V_{CC} = 2.3\text{V}$	—	8		
		$V_{CC} = 3\text{V}$	—	16		
		$V_{CC} = 4.5\text{V}$	—	24		
$\Delta t/\Delta V$	Input transition rise or fall rate	$V_{CC} = 1.8\text{V} \pm 0.15\text{V}, 2.5\text{V} \pm 0.2\text{V}$	—	20	ns/V	
		$V_{CC} = 3.3\text{V} \pm 0.3\text{V}$	—	10		
		$V_{CC} = 5\text{V} \pm 0.5\text{V}$	—	5		
$T_A$	Operating free-air temperature		—	-40	+125	$^\circ\text{C}$

Note: 5. Unused inputs should be held at  $V_{CC}$  or Ground.

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	-40°C to +85°C		-40°C to +125°C		Unit
				Min	Max	Min	Max	
V <sub>T+</sub>	Positive-going input threshold voltage	—	1.8V	0.70	1.50	0.70	1.70	V
			2.3V	1.00	1.80	1.00	2.00	
			3V	1.30	2.20	1.30	2.40	
			4.5V	1.90	3.10	1.90	3.30	
			5.5V	2.20	3.60	2.20	3.80	
V <sub>T-</sub>	Negative-going input threshold voltage	—	1.65V	0.25	0.90	0.39	1.10	V
			2.3V	0.40	1.15	0.25	0.87	
			3V	0.60	1.50	0.40	1.35	
			4.5V	1.00	2.00	0.60	1.70	
			5.5V	1.20	2.30	1.00	2.50	
ΔV <sub>T</sub>	Hysteresis (V <sub>T+</sub> - V <sub>T-</sub> )	—	1.8V	0.15	1.00	0.37	1.20	μA
			2.3V	0.25	1.10	0.15	1.30	
			3V	0.40	1.20	0.40	1.40	
			4.5V	0.60	1.50	0.60	1.70	
			5.5V	0.70	1.70	0.70	1.90	
V <sub>OH</sub>	High-Level Output Voltage	I <sub>OH</sub> = -100μA	1.65V to 4.5V	V <sub>CC</sub> - 0.1	—	V <sub>CC</sub> - 0.1	—	V
		I <sub>OH</sub> = -4mA	1.65V	1.2	—	0.95	—	
		I <sub>OH</sub> = -8mA	2.3V	1.9	—	1.7	—	
		I <sub>OH</sub> = -16mA	3V	2.4	—	1.9	—	
		I <sub>OH</sub> = -24mA		2.3	—	2.0	—	
		I <sub>OH</sub> = -32mA	4.5V	3.8	—	3.4	—	
V <sub>OL</sub>	Low-Level Output Voltage	I <sub>OL</sub> = 100μA	1.65V to 4.5V	—	0.1	—	0.10	V
		I <sub>OL</sub> = 4mA	1.65V	—	0.45	—	0.70	
		I <sub>OL</sub> = 8mA	2.3V	—	0.3	—	0.45	
		I <sub>OL</sub> = 16mA	3V	—	0.4	—	0.60	
		I <sub>OL</sub> = 24mA		—	0.55	—	0.80	
		I <sub>OL</sub> = 32mA	4.5V	—	0.55	—	0.80	
I <sub>I</sub>	Input Current	V <sub>I</sub> = 5.5V or GND	0 to 5.5V	—	± 5	—	± 20	μA
I <sub>OFF</sub>	Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 5.5V	0	—	± 10	—	± 20	μA
I <sub>CC</sub>	Supply Current	V <sub>I</sub> = 5.5V or GND, I <sub>O</sub> = 0	1.65V to 5.5V	—	10	—	40	μA

**Package Characteristics** (@T<sub>A</sub> = +25°C, V<sub>CC</sub> = 3.3V, unless otherwise specified.)

Symbol	Parameter	Package	Conditions	Min	Typ	Max	Unit
C <sub>i</sub>	Input Capacitance	Typical of all packages	V <sub>CC</sub> = 3.3V V <sub>I</sub> = V <sub>CC</sub> – or GND	—	3.5	—	pF
θ <sub>JA</sub>	Thermal Resistance Junction-to-Ambient	SOT26	(Note 6)	—	204	—	°C/W
		SOT363		—	371	—	
		X2-DFN1410-6		—	430	—	
		X2-DFN1409-6		—	450	—	
		X2-DFN1010-6		—	510	—	
θ <sub>JC</sub>	Thermal Resistance Junction-to-Case	SOT26	(Note 6)	—	52	—	°C/W
		SOT363		—	143	—	
		X2-DFN1410-6		—	190	—	
		X2-DFN1409-6		—	225	—	
		X2-DFN1010-6		—	250	—	

Note: 6. Test condition for SOT26, SOT363, X2-DFN1410-6, X2-DFN1409-6 and X2-DFN1010-6: Device mounted on FR-4 substrate PC board, 2oz copper with minimum recommended pad layout.

**Switching Characteristics**

T<sub>A</sub> = -40°C to +85°C, C<sub>L</sub> = 30 or 50pF (see Figure 1)

Parameter	From (Input)	TO (OUTPUT)	V <sub>CC</sub> = 1.8V ± 0.15V		V <sub>CC</sub> = 2.5V ± 0.2V		V <sub>CC</sub> = 3.3V ± 0.3V		V <sub>CC</sub> = 5V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A	Y	0.5	11.0	0.5	6.5	0.5	6.0	0.5	4.3	ns

T<sub>A</sub> = -40°C to +125°C, C<sub>L</sub> = 30 or 50pF (see Figure 1)

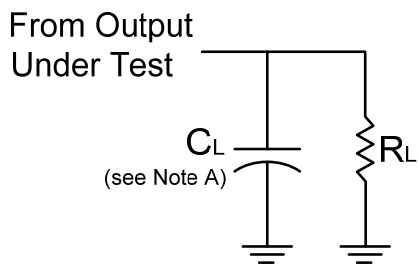
Parameter	From (Input)	TO (OUTPUT)	V <sub>CC</sub> = 1.8V ± 0.15V		V <sub>CC</sub> = 2.5V ± 0.2V		V <sub>CC</sub> = 3.3V ± 0.3V		V <sub>CC</sub> = 5V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A	Y	0.5	12.0	0.5	7.2	0.5	6.7	0.5	4.7	ns

**Operating Characteristics**

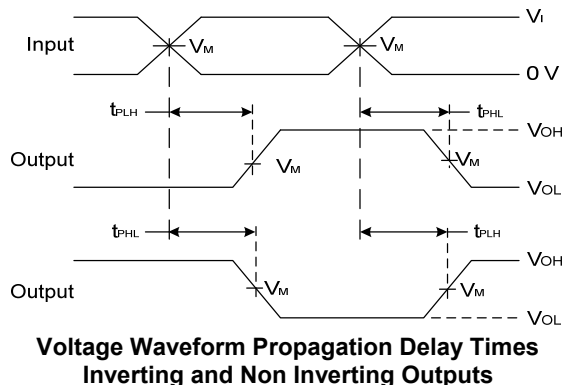
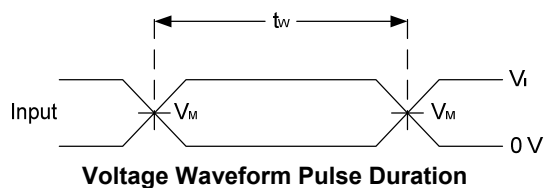
T<sub>A</sub> = +25°C

Parameter	Test Conditions	V <sub>CC</sub> = 1.8V	V <sub>CC</sub> = 2.5V	V <sub>CC</sub> = 3.3V	V <sub>CC</sub> = 5V	Unit
		Typ	Typ	Typ	Typ	
C <sub>pd</sub>	f = 10MHz	17	19	20	21	pF

**Parameter Measurement Information**



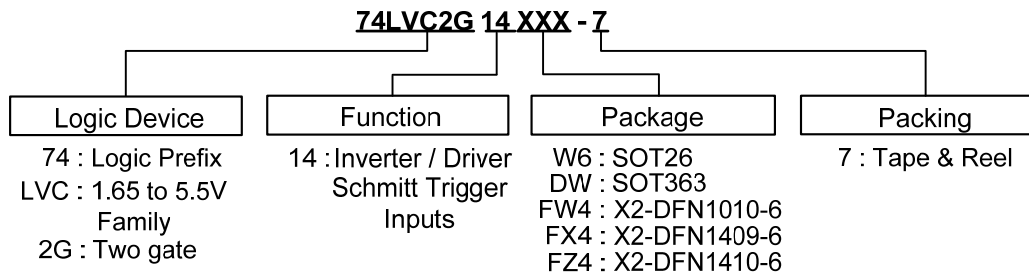
$V_{CC}$	Inputs		$V_M$	$C_L$	$R_L$
	$V_I$	$t_r/t_f$			
$1.8V \pm 0.15V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	30 pF	1k $\Omega$
$2.5V \pm 0.2V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	30 pF	500 $\Omega$
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	50 pF	500 $\Omega$
$5V \pm 0.5V$	$V_{CC}$	$\leq 2.5ns$	$V_{CC}/2$	50 pF	500 $\Omega$



**Figure 1. Load Circuit and Voltage Waveforms**

- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate  $\leq 10$  MHz.
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

## Ordering Information

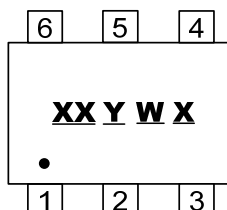


Device	Package Code	Packaging (Note 7)	7" Tape and Reel	
			Quantity	Part Number Suffix
74LVC2G14W6-7	W6	SOT26	3000/Tape & Reel	-7
74LVC2G14DW-7	DW	SOT363	3000/Tape & Reel	-7
74LVC2G14FW4-7	FW4	X2-DFN1010-6	5000/Tape & Reel	-7
74LVC2G14FX4-7	FX4	X2-DFN1409-6	5000/Tape & Reel	-7
74LVC2G14FZ4-7	FZ4	X2-DFN1410-6	5000/Tape & Reel	-7

Note: 7. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>

## Marking Information

### (1) SOT26, SOT363

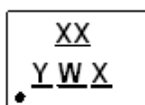


**XX** : Identification code  
**Y** : Year 0~9  
**W** : Week : A~Z : 1~26 week;  
       a~z : 27~52 week; z represents  
       52 and 53 week  
**X** : A~Z : Internal Code

Part Number	Package	Identification Code
74LVC2G14W6	SOT26	Z5
74LVC2G14DW	SOT363	Z5

### (2) X2-DFN1010-6, X2-DFN1409-6, X2-DFN1410-6

#### (Top View)



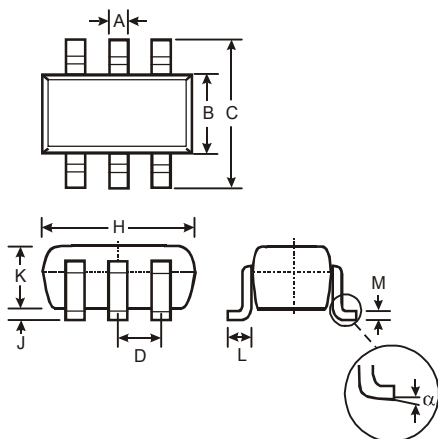
**XX** : Identification Code  
**Y** : Year : 0~9  
**W** : Week : A~Z : 1~26 week;  
       a~z : 27~52 week; z represents  
       52 and 53 week  
**X** : A~Z : Internal code

Part Number	Package	Identification Code
74LVC2G14FW4	X2-DFN1010-6	Z5
74LVC2G14FX4	X2-DFN1409-6	X5
74LVC2G14FZ4	X2-DFN1410-6	Z5

**Package Outline Dimensions** (All dimensions in mm.)

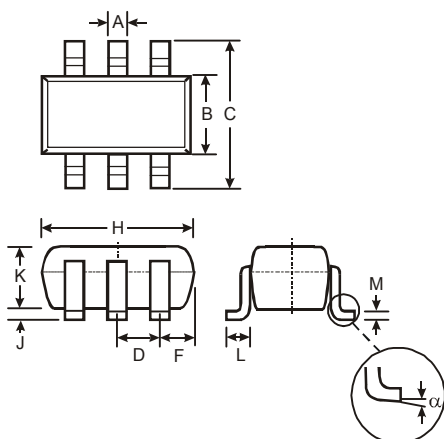
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

**(1) Package Type: SOT26**



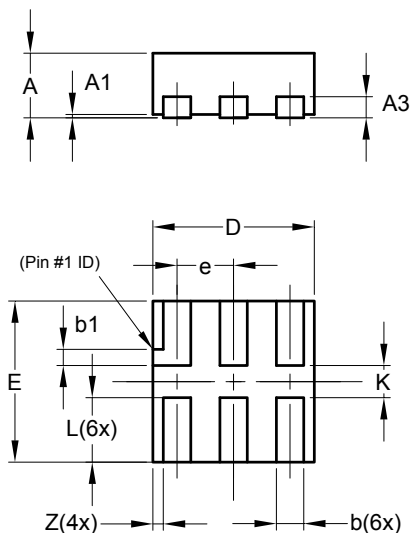
SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

**(2) Package Type: SOT363**



SOT363			
Dim	Min	Max	Typ
A	0.10	0.30	0.25
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	0.65 Typ		
F	0.40	0.45	0.425
H	1.80	2.20	2.15
J	0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.22	0.11
α	0°	8°	-
All Dimensions in mm			

**(3) Package Type: X2-DFN1010-6**



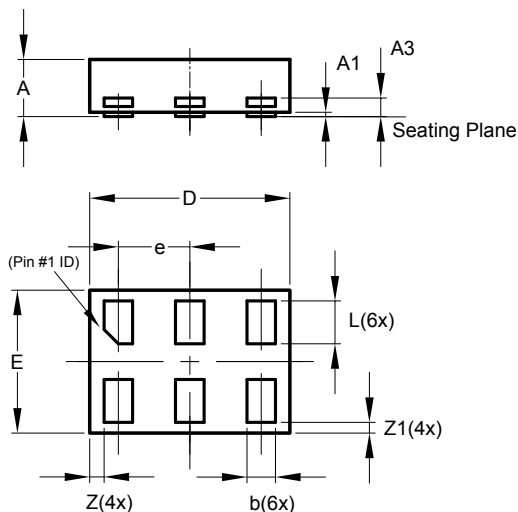
X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			



**Package Outline Dimensions** (cont.) (All dimensions in mm.)

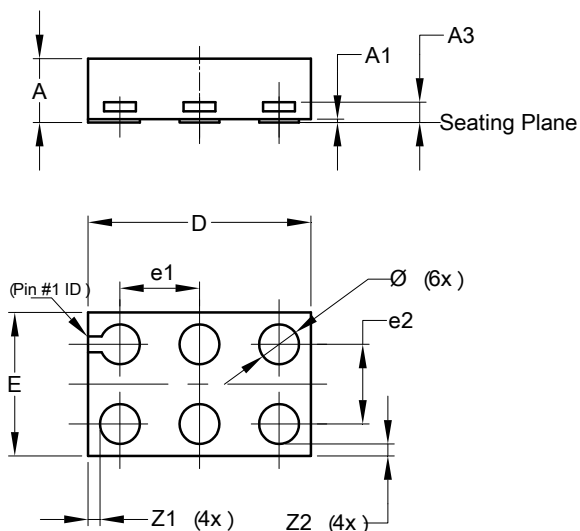
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

**(4) Package Type X2-DFN1410-6**



X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

**(5) Package Type: X2-DFN1409-6 Chip Scale Replacement**

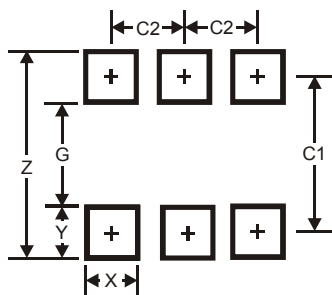


X2-DFN1409-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0	0.05	0.02
A3	—	—	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	—	—	0.50
e2	—	—	0.50
Z1	—	—	0.075
Z2	—	—	0.075
All Dimensions in mm			

## Suggested Pad Layout

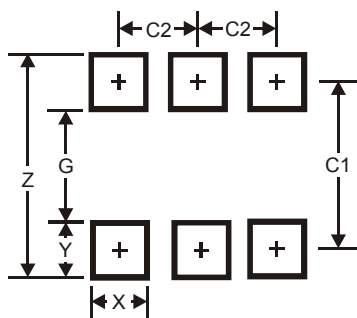
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

### (1) Package Type: SOT26



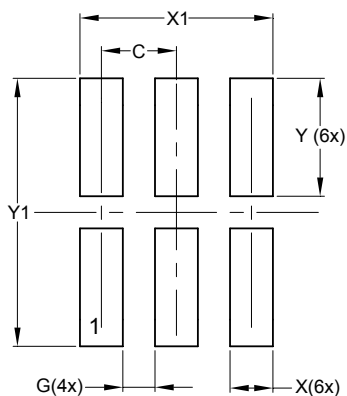
Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

### (2) Package Type: SOT363



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

### (3) Package Type: X2-DFN1010-6

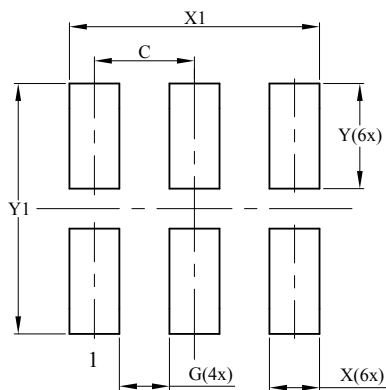


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

**Suggested Pad Layout (cont.)**

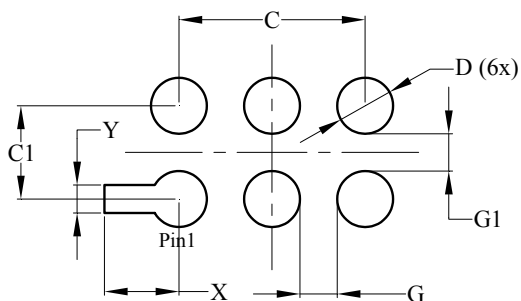
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

**(4) Package Type X2-DFN1410-6**



Dimensions	Value (in mm)
<b>C</b>	0.500
<b>G</b>	0.250
<b>X</b>	0.250
<b>X1</b>	1.250
<b>Y</b>	0.525
<b>Y1</b>	1.250

**(5) Package Type: X2-DFN1409-6 Chip Scale Replacement**



Dimensions	Value (in mm)
<b>C</b>	1.000
<b>C1</b>	0.500
<b>D</b>	0.300
<b>G</b>	0.200
<b>G1</b>	0.200
<b>X</b>	0.400
<b>Y</b>	0.150

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